

SOT464-1

plastic, heatsink shrink quad flat package; 240 leads; body 32 x 32 x 3.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HSQFP240
Package type industry code	HSQFP240
Package style descriptive code	HSQFP (thermal enhanced shrink quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-11-1999

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		31.9	-	32	32.1	mm
E	package width		31.9	-	32	32.1	mm
A	seated height		[tbd]	-	4.1	4.1	mm
A ₂	package height		3.3	-	3.4	3.5	mm
n ₂	actual quantity of termination		-	-	240	-	

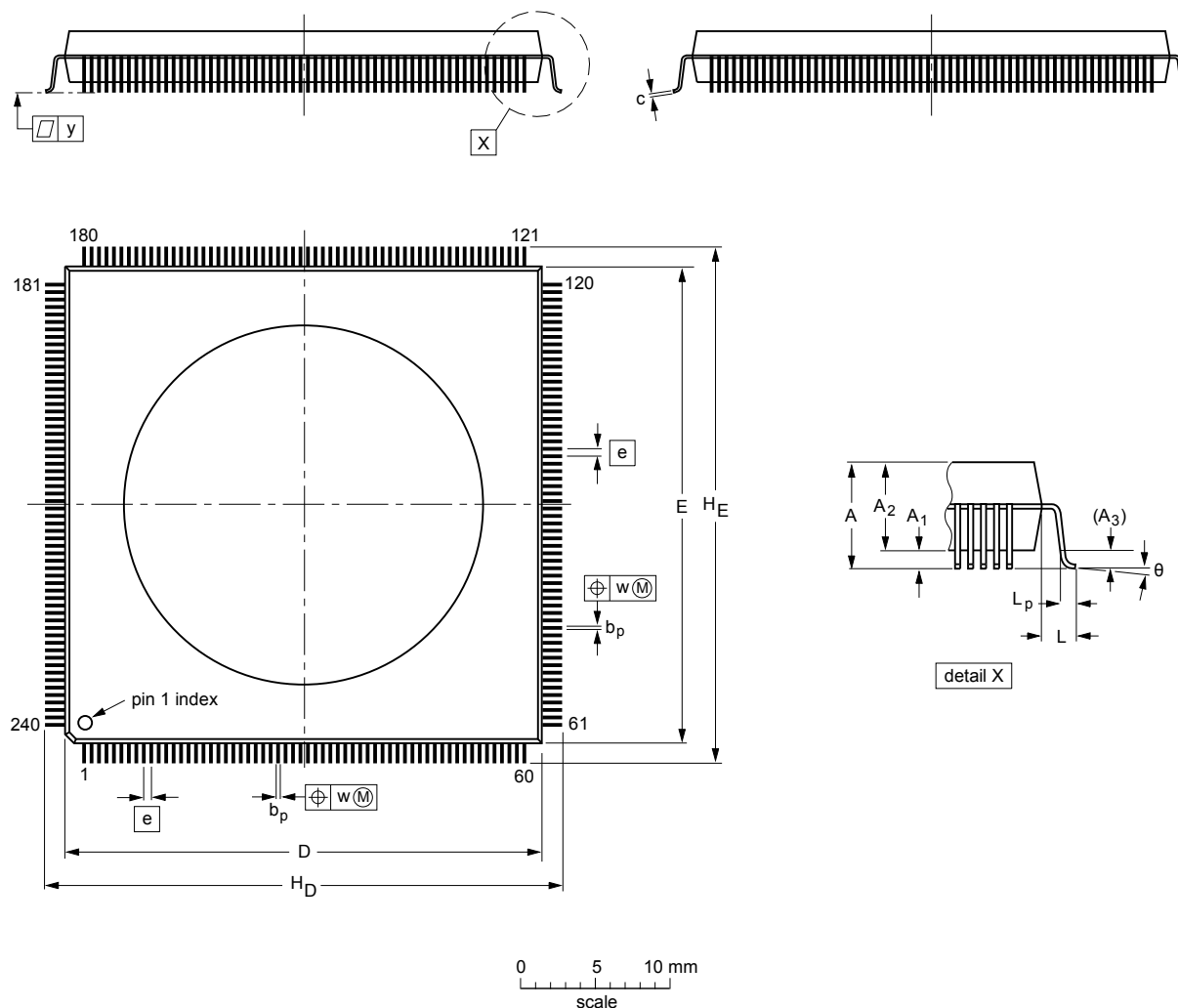


**plastic, heatsink shrink quad flat package; 240
leads; body 32 x 32 x 3.4 mm**

2. Package outline

HSQFP240: plastic, heatsink shrink quad flat package; 240 leads; body 32 x 32 x 3.4 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max.}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	w	y	θ
mm	4.10	0.25	3.50 3.30	0.25	0.27 0.17	0.17	32.1 31.9	32.1 31.9	0.5	34.85 34.35	34.85 34.35	1.30	0.75 0.50	0.08	0.08	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.



OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT464-1					 	96-10-11- 99-11-12

Fig. 1. Package outline HSQFP240 (SOT464-1)

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3. Legal information

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